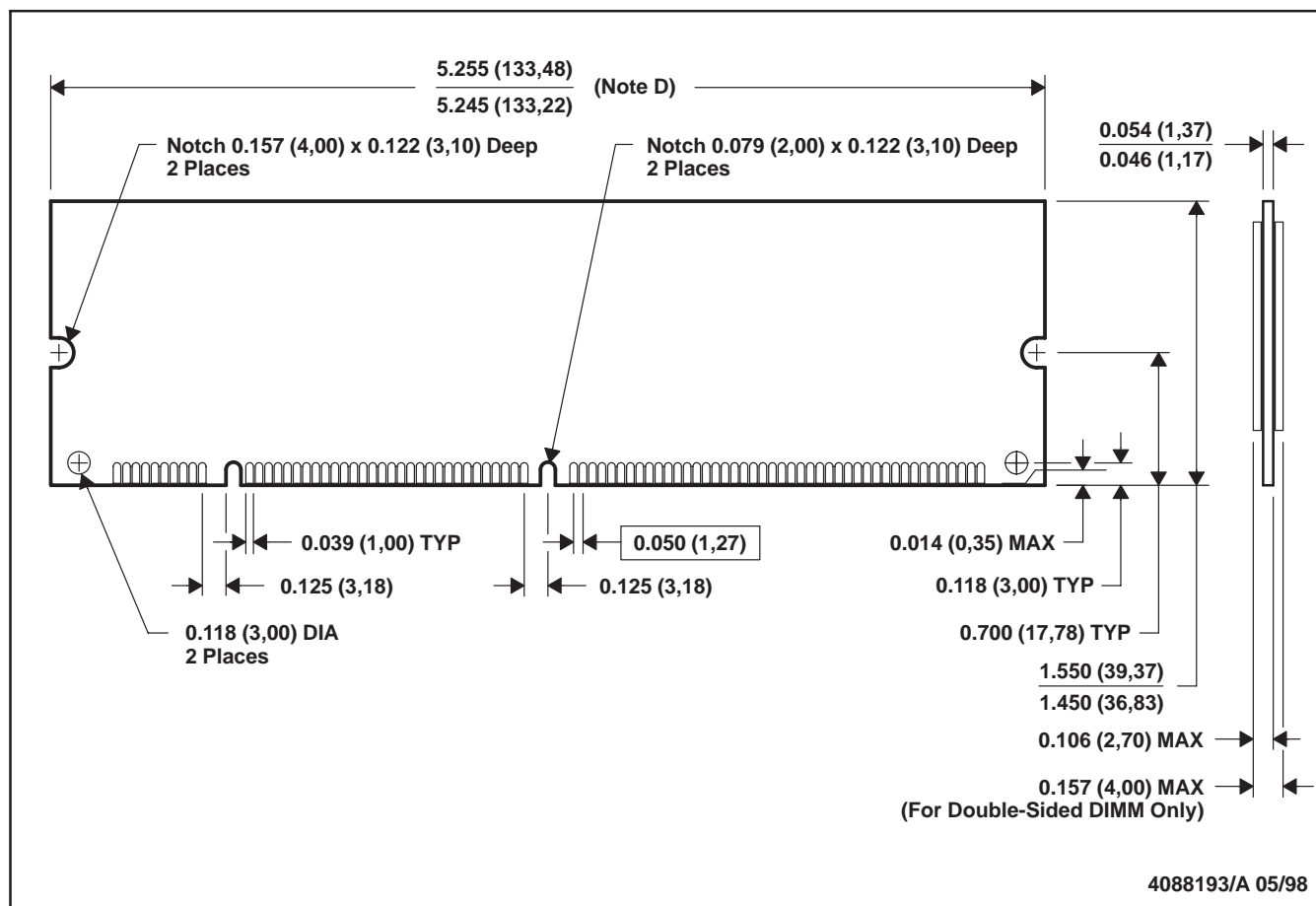


## BVC (R-PDIM-N168)

## DUAL-IN-LINE MEMORY MODULE



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC MO-161  
 D. Dimension includes depanelization variations; applies between notch and tab edge.  
 E. Outline may vary above notches to allow router/panelization irregularities.

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